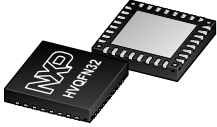


SOT617-26(D)

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

13 February 2024

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	02-01-2024
Manufacturer package code	98ASA01797D

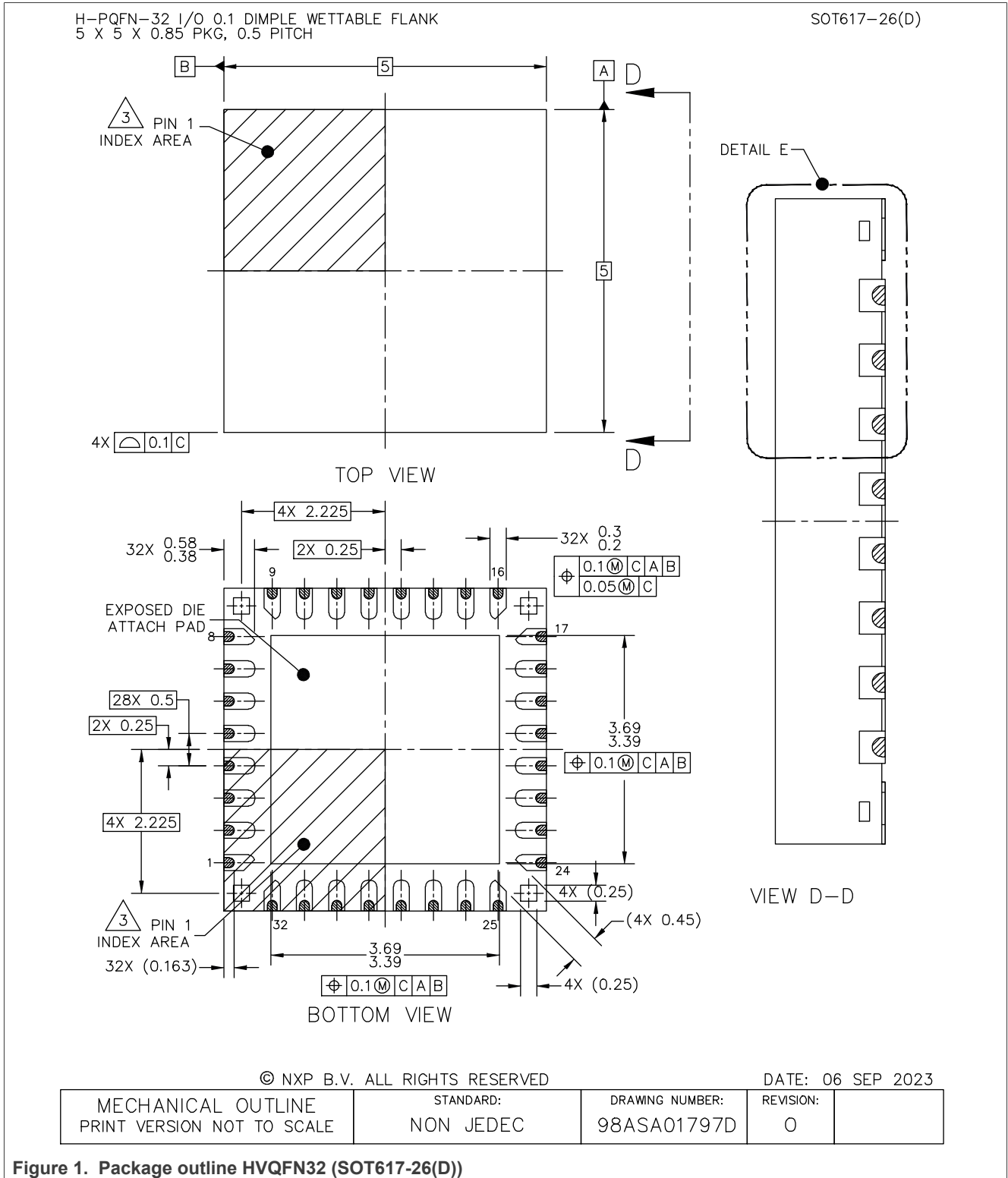
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

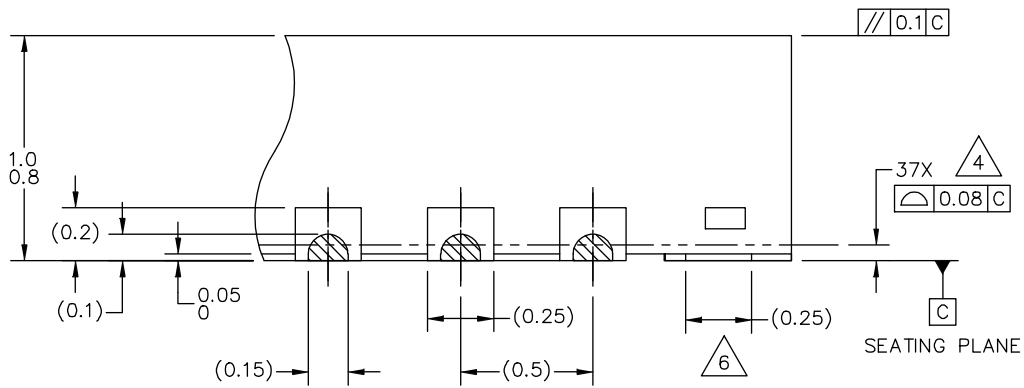
2 Package outline



HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

H-PQFN-32 I/O 0.1 DIMPLE WETTABLE FLANK
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-26(D)



DETAIL E
VIEW ROTATED 90° CW

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DATE: 06 SEP 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01797D	REVISION: 0
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Figure 2. Package outline detail E of HVQFN32 (SOT617-26(D))

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

3 Soldering

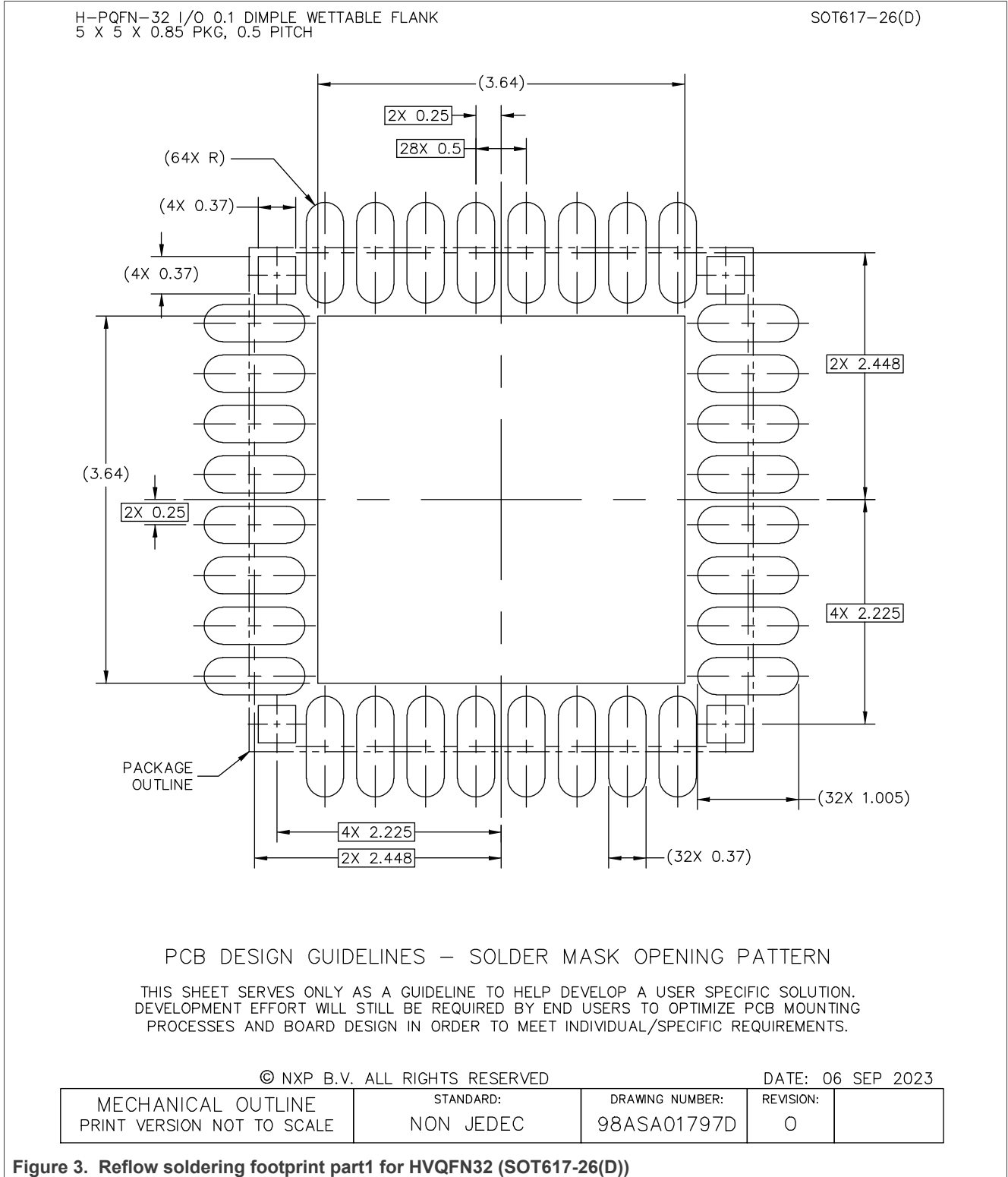
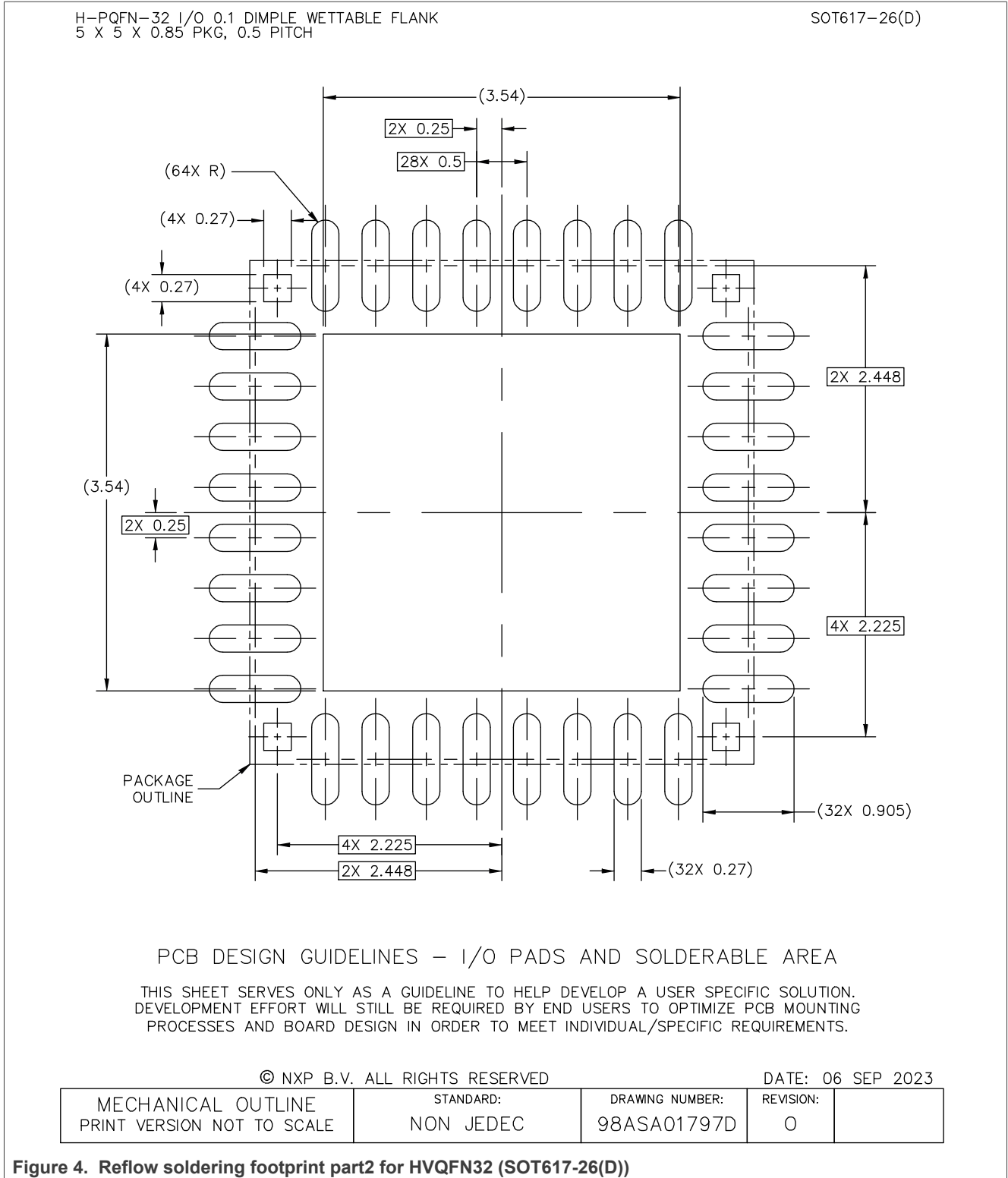


Figure 3. Reflow soldering footprint part1 for HVQFN32 (SOT617-26(D))

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body



HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

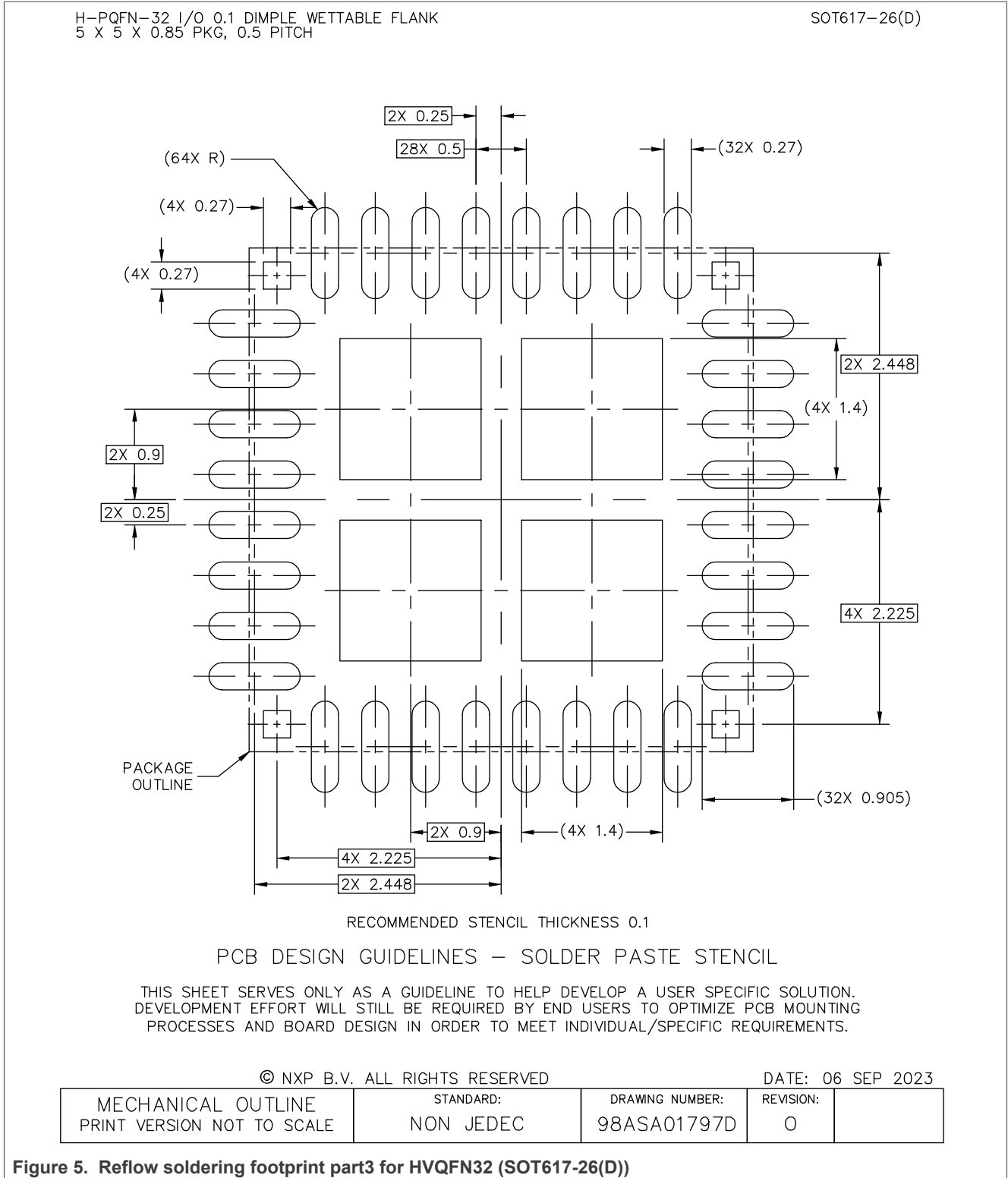


Figure 5. Reflow soldering footprint part3 for HVQFN32 (SOT617-26(D))

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals,
0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

H-PQFN-32 1/0 0.1 DIMPLE WETTABLE FLANK
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-26(D)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN32 (SOT617-26(D))

HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals,
0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

4 Legal information

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HVQFN32, thermal enhanced very thin quad flat package, no leads, wettable flanks, 32 terminals,
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